

ABSTRACT

A resin-sealing and molding apparatus furnished with sealing mechanism. The sealing mechanism includes upper-die-side ambient air shutoff member (11) fixed to upper-die-side mount base board (15) so as to surround the lateral side of upper die (1) and lower-die-side ambient air shutoff member (12) fixed to lower-die-side mount base board (16) so as to surround the lateral side of lower die (2). The upper-die-side ambient air shutoff member (11) is fixed to the upper-die-side mount base board (15) by means of upper-die-side fixing tool (24). The lower-die-side ambient air shutoff member (12) is fixed to the lower-die-side mount base board (16) by means of lower-die-side fixing tool (27). The upper-die-side ambient air shutoff member (11) and the upper-die-side mount base board (15) are pivotably connected by means of axis member (22). Only by dismounting of the lower-die-side fixing tool (27) from the lower-die-side mount base board (16) and the lower-die-side ambient air shutoff member (12), there can be realized the state in which the lower-die-side ambient air shutoff member (12) can be completely dismounted from the lower-die-side mount base board (16).